DESCRIPTION

A flip chip solder surface mount resistive divider ideal for applications where small size and broad band performance are critical for success. The splitter offers low excessive loss from DC to 20GHz in addition to 20dB of return loss on all ports. This component is ideal for test and measurement and optical applications.

FEATURES

- Small Size
- Excellent Repeatability
- Frequency Stable over Temperature
- Flip Chip Solder Surface Mountable
- Moisture Sensitivity Level: MSL1
- Operating & Storage Temp: -55°C to +125°C
- Characteristic Impedance: 50Ω

SPECIFICATIONS*

<table>
<thead>
<tr>
<th>Passband (GHz)</th>
<th>DC to 20GHz</th>
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</thead>
<tbody>
<tr>
<td>Excess Insertion Loss (dB)</td>
<td>0.25 dB typ @ 25°C</td>
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<tr>
<td>Return Loss (dB)</td>
<td>20dB typ @ 25°C</td>
</tr>
<tr>
<td>Size (LxWxH)</td>
<td>0.075 x 0.070 x 0.010 in</td>
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<td></td>
<td>1.905 x 1.778 x 0.254 mm</td>
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</tbody>
</table>

*Electrical specifications based on anticipated performance judged from simulation data. Final specification TBD.
Physical Dimensions

Units = mils

- 50Ω trace dimensions are application specific.
- Ensure adequate grounding beneath the part.

Recommended PCB Layout